

STARPOWER

SEMICONDUCTOR

IGBT

GD300TLL120C2S

Molding Type Module

1200V/300A 3-level in one-package

General Description

STARPOWER IGBT Power Module provides ultra low conduction loss as well as short circuit ruggedness. They are designed for the applications such as UPS.



Features

- Low $V_{CE(sat)}$ SPT+ IGBT technology
- 10 μ s short circuit capability
- $V_{CE(sat)}$ with positive temperature coefficient
- Maximum junction temperature 175 °C
- Low inductance case
- Fast & soft reverse recovery anti-parallel FWD
- Isolated copper baseplate using DBC technology

Typical Applications

- Solar power
- UPS

TI,T2 IGBT $T_C=25^{\circ}\text{C}$ unless otherwise noted**Maximum Rated Values**

Symbol	Description	GD300TLL120C2S	Units
V_{CES}	Collector-Emitter Voltage @ $T_j=25^{\circ}\text{C}$	1200	V
V_{GES}	Gate-Emitter Voltage @ $T_j=25^{\circ}\text{C}$	± 20	V
I_C	Collector Current @ $T_C=25^{\circ}\text{C}$	490	A
	@ $T_C=100^{\circ}\text{C}$	300	
I_{CM}	Pulsed Collector Current $t_p=1\text{ms}$	600	A
P_{tot}	Total Power Dissipation @ $T_j=175^{\circ}\text{C}$	1875	W

Off Characteristics

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$V_{(BR)CES}$	Collector-Emitter Breakdown Voltage	$T_j=25^{\circ}\text{C}$	1200			V
I_{CES}	Collector Cut-Off Current	$V_{CE}=V_{CES}, V_{GE}=0\text{V}, T_j=25^{\circ}\text{C}$			5.0	mA
I_{GES}	Gate-Emitter Leakage Current	$V_{GE}=V_{GES}, V_{CE}=0\text{V}, T_j=25^{\circ}\text{C}$			400	nA

On Characteristics

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$V_{GE(th)}$	Gate-Emitter Threshold Voltage	$I_C=12.0\text{mA}, V_{CE}=V_{GE}, T_j=25^{\circ}\text{C}$	5.0	6.2	7.0	V
$V_{CE(sat)}$	Collector to Emitter Saturation Voltage	$I_C=300\text{A}, V_{GE}=15\text{V}, T_j=25^{\circ}\text{C}$		2.00	2.45	V
		$I_C=300\text{A}, V_{GE}=15\text{V}, T_j=125^{\circ}\text{C}$		2.20		

Switching Characteristics

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$t_{d(on)}$	Turn-On Delay Time	$V_{CC}=600V, I_C=300A,$ $R_G=4.7\Omega, V_{GE}=\pm 15V,$ $T_j=25^\circ C$		574		ns
t_r	Rise Time			133		ns
$t_{d(off)}$	Turn-Off Delay Time			563		ns
t_f	Fall Time			120		ns
E_{on}	Turn-On Switching Loss			23.9		mJ
E_{off}	Turn-Off Switching Loss			25.3		mJ
$t_{d(on)}$	Turn-On Delay Time	$V_{CC}=600V, I_C=300A,$ $R_G=4.7\Omega, V_{GE}=\pm 15V,$ $T_j=125^\circ C$		604		ns
t_r	Rise Time			137		ns
$t_{d(off)}$	Turn-Off Delay Time			629		ns
t_f	Fall Time			167		ns
E_{on}	Turn-On Switching Loss			31.5		mJ
E_{off}	Turn-Off Switching Loss			35.9		mJ
C_{ies}	Input Capacitance	$V_{CE}=25V, f=1Mhz,$ $V_{GE}=0V$		21.2		nF
C_{res}	Reverse Transfer Capacitance			0.94		nF
Q_G	Gate Charge	$V_{CC}=600V, I_C=300A,$ $V_{GE}=-15 \dots +15V$		3.1		nC
R_{Gint}	Internal Gate Resister			1.0		Ω
I_{SC}	SC Data	$t_p \leq 10\mu s, V_{GE}=15V,$ $T_j=125^\circ C, V_{CC}=900V,$ $V_{CEM} \leq 1200V$		1300		A

TI, T2 Diode $T_C=25^\circ C$ unless otherwise noted

Maximum Rated Values

Symbol	Description	GD300TLL120C2S	Units
V_{RRM}	Repetitive Peak Reverse Voltage @ $T_j=25^\circ C$	1200	V
I_F	DC Forward Current	300	A
I_{FRM}	Repetitive Peak Forward Current $t_p=1ms$	600	A

Characteristics Values

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units	
V_F	Diode Forward Voltage	$I_F=300A,$ $V_{GE}=0V$	$T_j=25^\circ C$		1.65	2.15	V
			$T_j=125^\circ C$		1.65		
Q_r	Recovered Charge	$I_F=300A,$ $V_R=600V,$ $R_G=2.4\Omega,$ $V_{GE}=-15V$	$T_j=25^\circ C$		30		μC
			$T_j=125^\circ C$		55		
I_{RM}	Peak Reverse Recovery Current	$V_R=600V,$ $R_G=2.4\Omega,$ $V_{GE}=-15V$	$T_j=25^\circ C$		210		A
			$T_j=125^\circ C$		270		
E_{rec}	Reverse Recovery Energy	$V_R=600V,$ $R_G=2.4\Omega,$ $V_{GE}=-15V$	$T_j=25^\circ C$		13.9		mJ
			$T_j=125^\circ C$		26.1		

T3,T4 IGBT $T_C=25^\circ\text{C}$ unless otherwise noted**Maximum Rated Values**

Symbol	Description	GD300TLL120C2S	Units
V_{CES}	Collector-Emitter Voltage @ $T_j=25^\circ\text{C}$	650	V
V_{GES}	Gate-Emitter Voltage @ $T_j=25^\circ\text{C}$	± 20	V
I_C	Collector Current @ $T_C=25^\circ\text{C}$	480	A
	@ $T_C=100^\circ\text{C}$	300	
I_{CM}	Pulsed Collector Current $t_p=1\text{ms}$	600	A
P_{tot}	Total Power Dissipation @ $T_j=175^\circ\text{C}$	1071	W

Off Characteristics

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$V_{(BR)CES}$	Collector-Emitter Breakdown Voltage	$T_j=25^\circ\text{C}$	650			V
I_{CES}	Collector Cut-Off Current	$V_{CE}=V_{CES}, V_{GE}=0\text{V},$ $T_j=25^\circ\text{C}$			5.0	mA
I_{GES}	Gate-Emitter Leakage Current	$V_{GE}=V_{GES}, V_{CE}=0\text{V},$ $T_j=25^\circ\text{C}$			400	nA

On Characteristics

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$V_{GE(th)}$	Gate-Emitter Threshold Voltage	$I_C=13.2\text{mA}, V_{CE}=V_{GE},$ $T_j=25^\circ\text{C}$	5.5		7.7	V
$V_{CE(sat)}$	Collector to Emitter Saturation Voltage	$I_C=300\text{A}, V_{GE}=15\text{V},$ $T_j=25^\circ\text{C}$		1.50	1.95	V
		$I_C=300\text{A}, V_{GE}=15\text{V},$ $T_j=175^\circ\text{C}$		1.80		

Switching Characteristics

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$t_{d(on)}$	Turn-On Delay Time	$V_{CC}=300V, I_C=300A,$ $R_G=2.5\Omega, V_{GE}=\pm 15V,$ $T_j=25^\circ C$		125		ns
t_r	Rise Time			320		ns
$t_{d(off)}$	Turn-Off Delay Time			270		ns
t_f	Fall Time			135		ns
E_{on}	Turn-On Switching Loss			3.20		mJ
E_{off}	Turn-Off Switching Loss			12.2		mJ
$t_{d(on)}$	Turn-On Delay Time	$V_{CC}=300V, I_C=300A,$ $R_G=2.5\Omega, V_{GE}=\pm 15V,$ $T_j=125^\circ C$		110		ns
t_r	Rise Time			320		ns
$t_{d(off)}$	Turn-Off Delay Time			320		ns
t_f	Fall Time			145		ns
E_{on}	Turn-On Switching Loss			3.50		mJ
E_{off}	Turn-Off Switching Loss			12.8		mJ
C_{ies}	Input Capacitance	$V_{CE}=30V, f=1Mhz,$ $V_{GE}=0V$		25.9		nF
C_{res}	Reverse Transfer Capacitance			0.68		nF
Q_G	Gate Charge	$V_{CC}=300V, I_C=300A,$ $V_{GE}=15V$		590		nC
R_{Gint}	Internal Gate Resister			1.0		Ω
I_{SC}	SC Data	$t_p \leq 6\mu s, V_{GE}=15V,$ $T_j=125^\circ C, V_{CC}=360V,$ $V_{CEM} \leq 650V$		3600		A

T3,T4 Diode $T_C=25^\circ C$ unless otherwise noted

Maximum Rated Values

Symbol	Description	GD300TLL120C2S	Units
V_{RRM}	Repetitive Peak Reverse Voltage @ $T_j=25^\circ C$	650	V
I_F	DC Forward Current	300	A
I_{FRM}	Repetitive Peak Forward Current $t_p=1ms$	600	A

Characteristics Values

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
V_F	Diode Forward Vd tage	$I_F=300A,$ $V_{GE}=0V$	$T_j=25^\circ C$	1.40	1.80	V
			$T_j=125^\circ C$	1.40		
Q_r	Recovered Charge	$I_F=300A,$ $V_R=300V,$ $R_G=4.7\Omega,$ $V_{GE}=-15V$	$T_j=25^\circ C$	12.0		μC
			$T_j=125^\circ C$	21.2		
I_{RM}	Peak Reverse Recovery Current	$V_R=300V,$ $R_G=4.7\Omega,$ $V_{GE}=-15V$	$T_j=25^\circ C$	153		A
			$T_j=125^\circ C$	185		
E_{rec}	Reverse Recovery Energy	$V_R=300V,$ $R_G=4.7\Omega,$ $V_{GE}=-15V$	$T_j=25^\circ C$	2.65		mJ
			$T_j=125^\circ C$	5.12		

IGBT Module

Symbol	Parameter	Min.	Typ.	Max.	Units
V_{ISO}	Isolation Voltage RMS, f=50Hz, t=1min	4000			V
$R_{\theta JC}$	Junction-to-Case (per T1, T2 IGBT)			0.080	K/W
	Junction-to-Case (per T1, T2 Diode)			0.158	
	Junction-to-Case (per T3, T4 IGBT)			0.137	
	Junction-to-Case (per T3, T4 Diode)			0.236	
$R_{\theta CS}$	Case-to-Sink (Conductive grease applied)		0.035		K/W
T_{jmax}	Maximum Junction Temperature			175	°C
T_{jop}	Operating Junction Temperature	-40		150	°C
T_{STG}	Storage Temperature Range	-40		125	°C
M	Terminal Connection Torque, Screw M6	2.5		5.0	N.m
	Mounting Torque, Screw M6	3.0		5.0	
G	Weight of Module		340		g

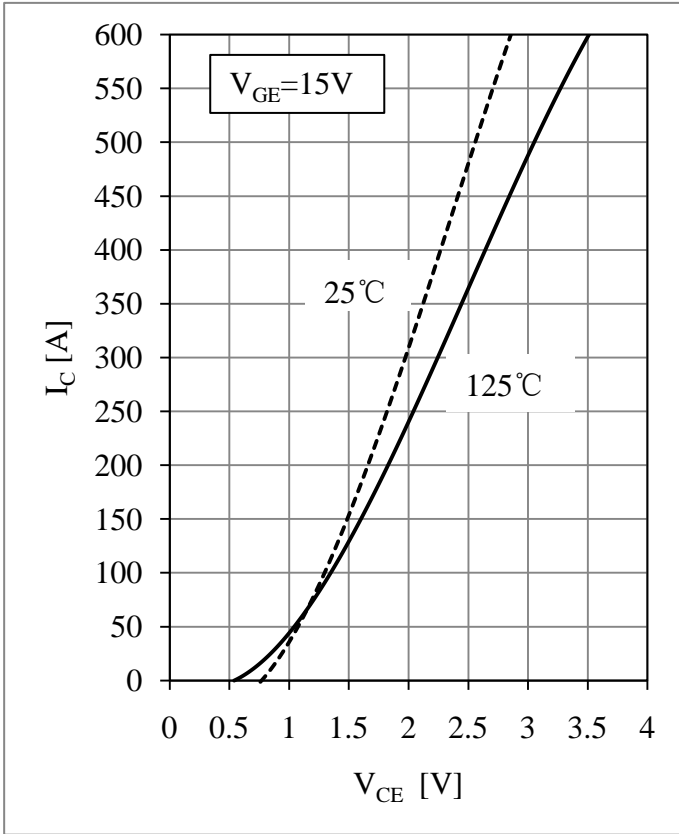


Fig 1. IGBT Output Characteristics (T1,T2)

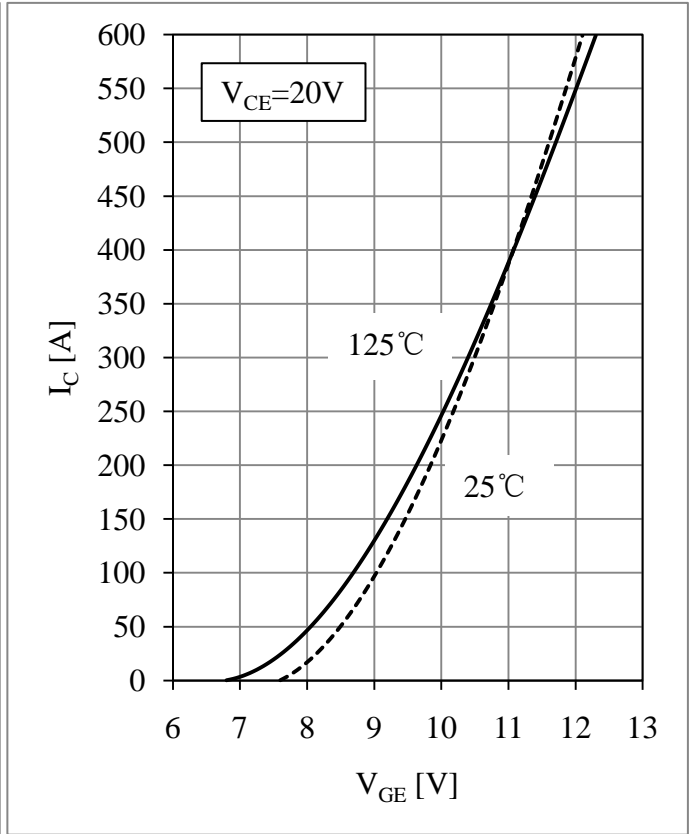


Fig 2. IGBT Transfer Characteristics (T1,T2)

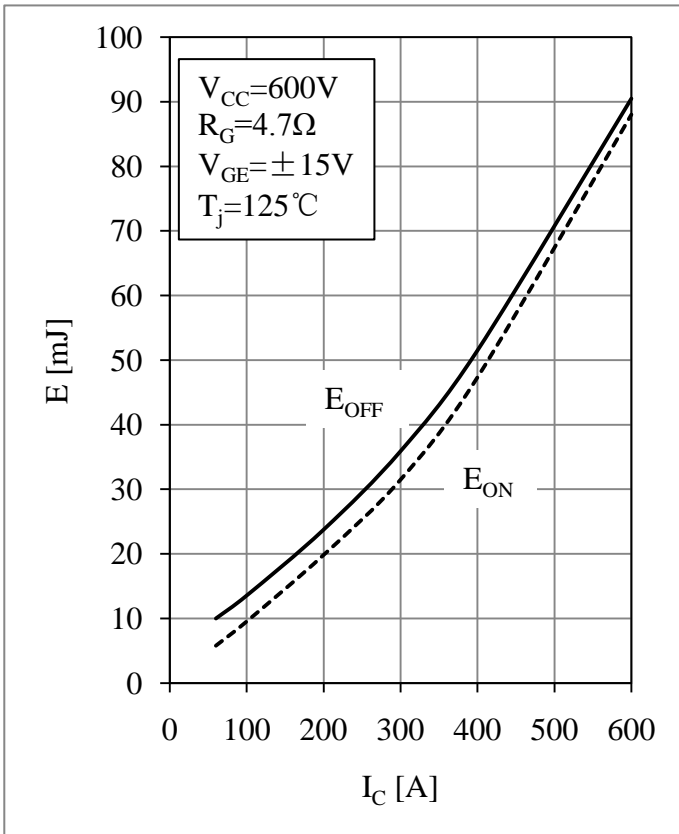


Fig 3. IGBT Switching Loss vs. I_C (T1,T2)

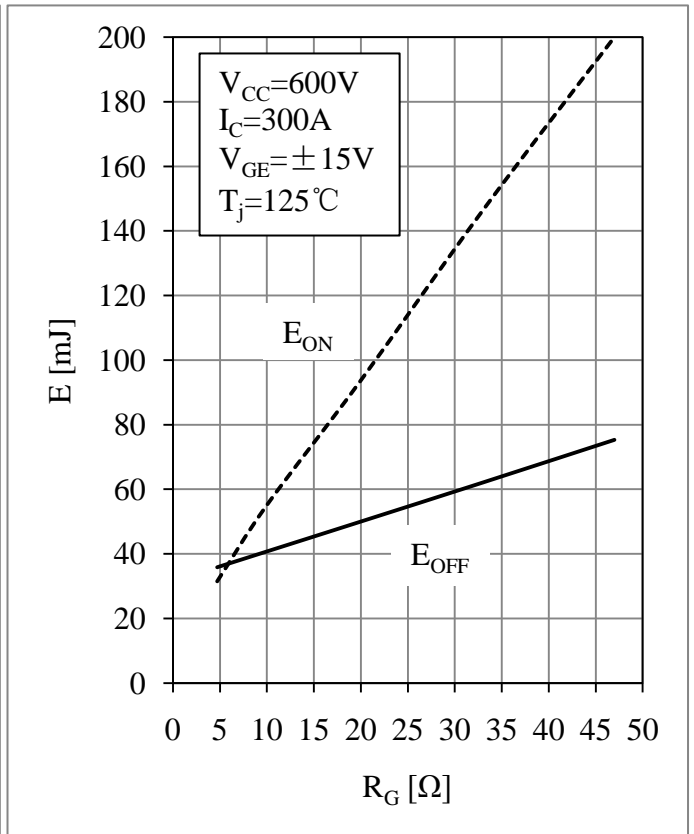


Fig 4. IGBT Switching Loss vs. R_G (T1,T2)

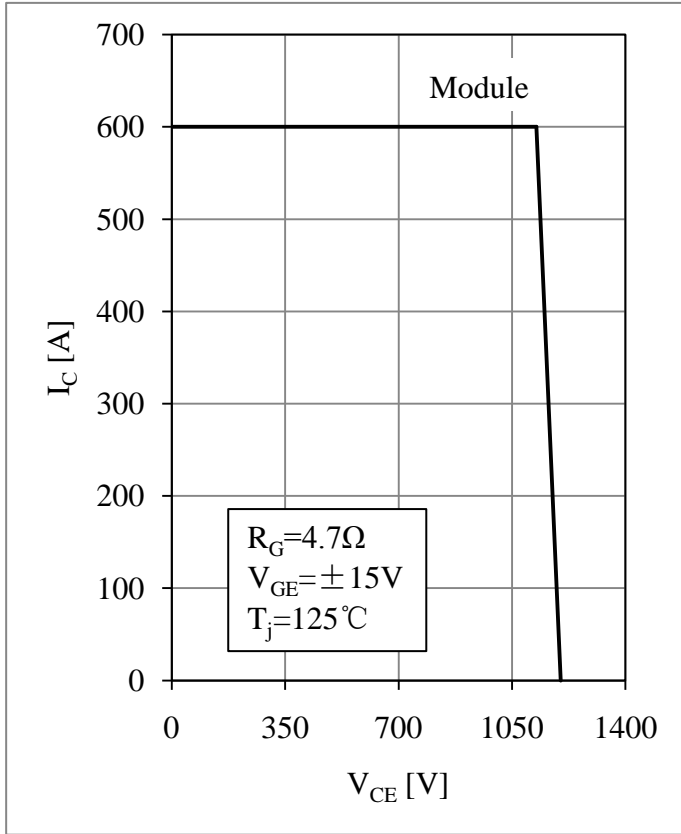


Fig 5. RBSOA (T1,T2)

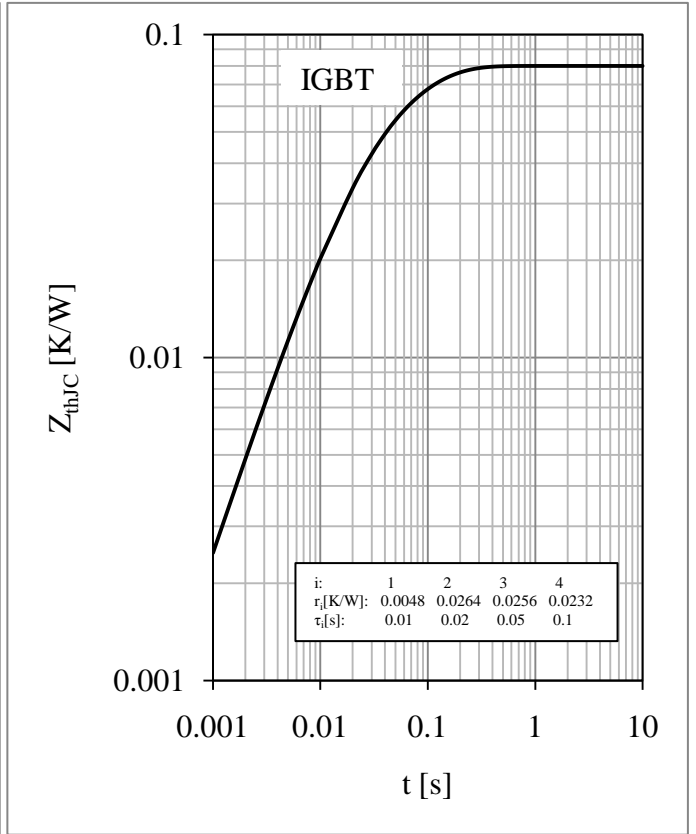


Fig 6. IGBT Transient Thermal Impedance (T1,T2)

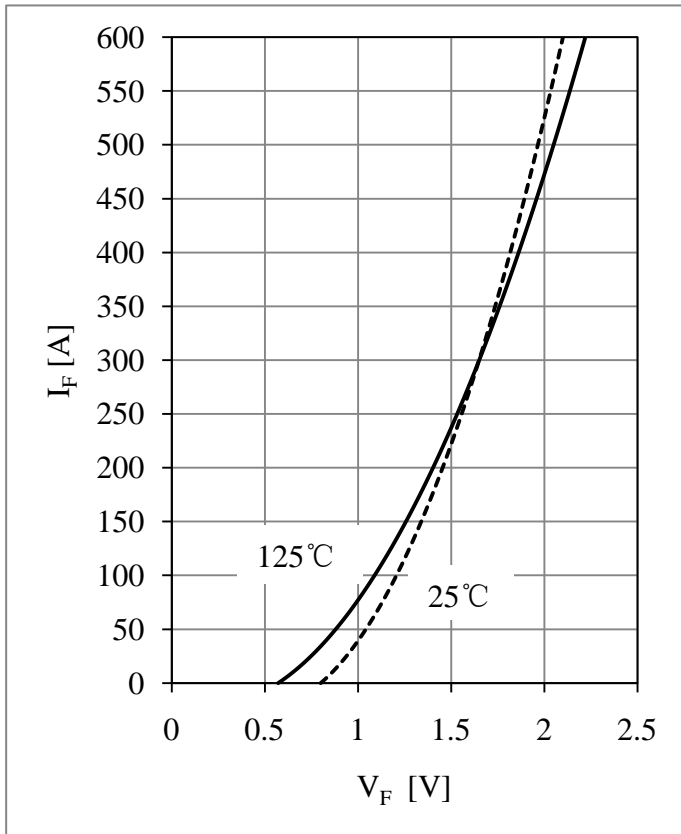


Fig 7. Diode Forward Characteristics (T1,T2)

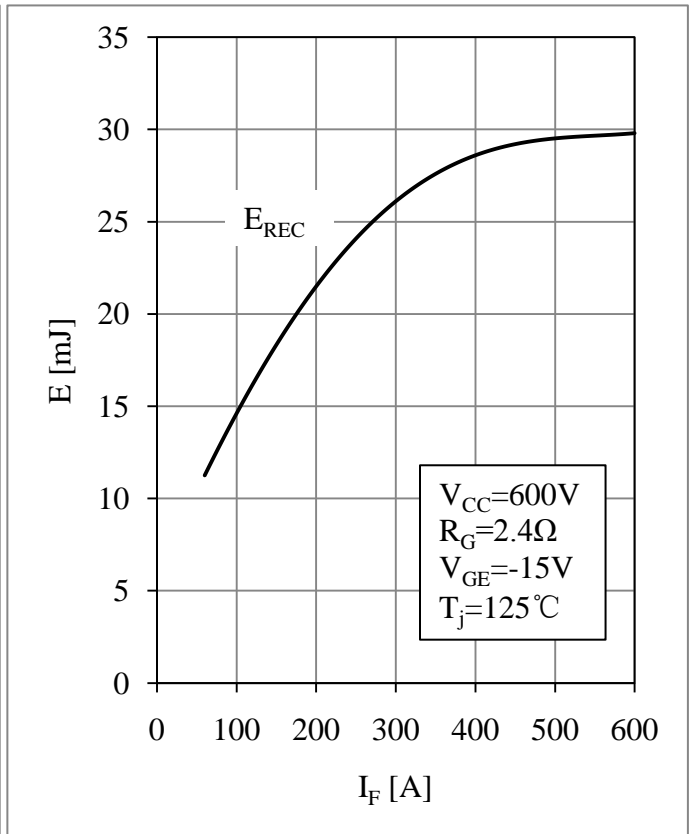


Fig 8. Diode Switching Loss vs. I_F (T1,T2)

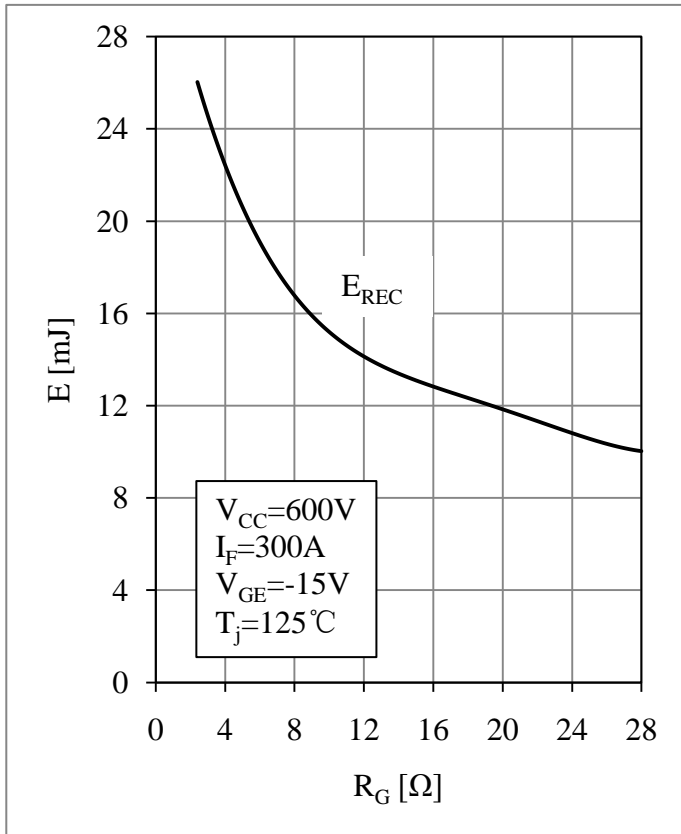


Fig 9. Diode Switching Loss vs. R_G (T1,T2)

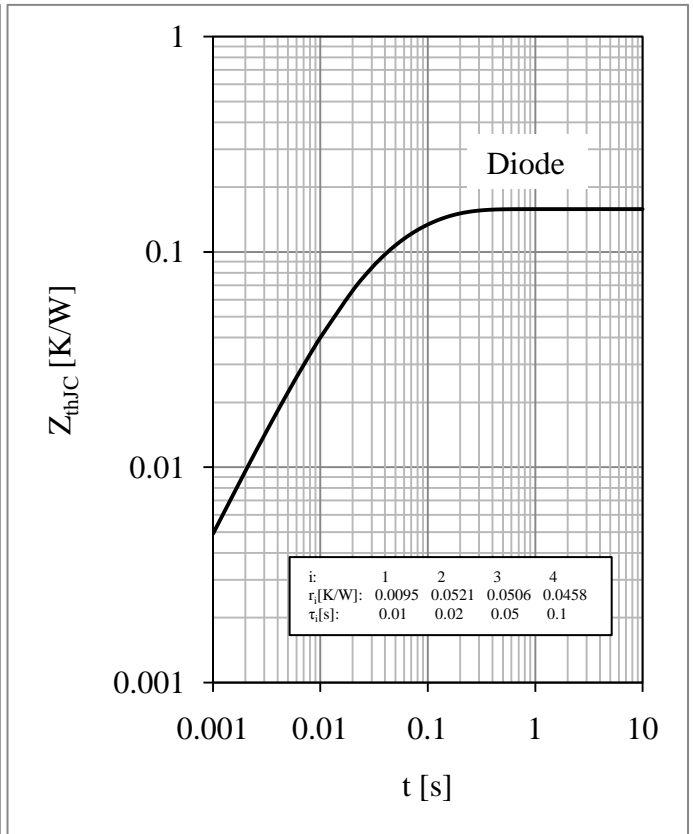


Fig 10. Diode Transient Thermal Impedance (T1,T2)

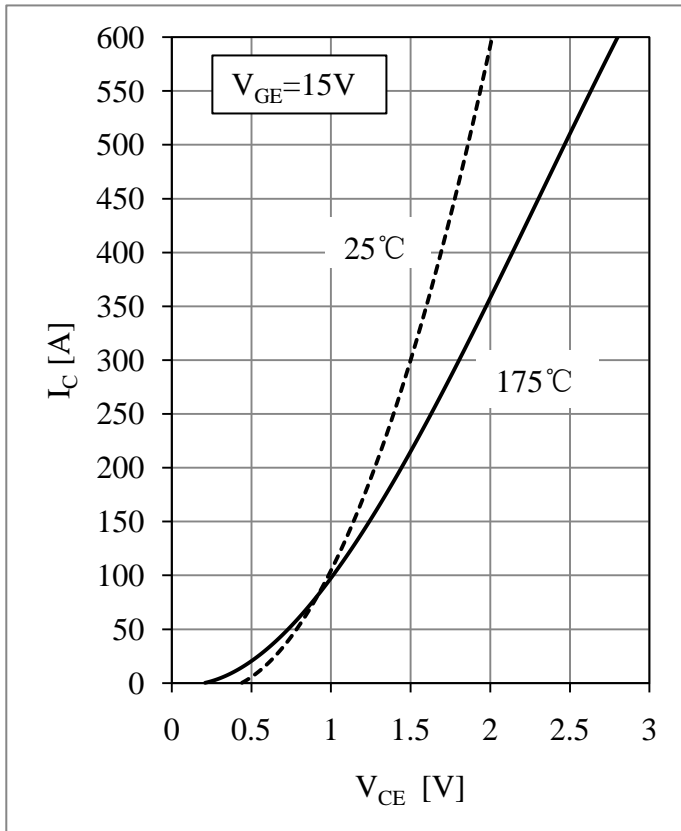


Fig 11. IGBT Output Characteristics (T3,T4)

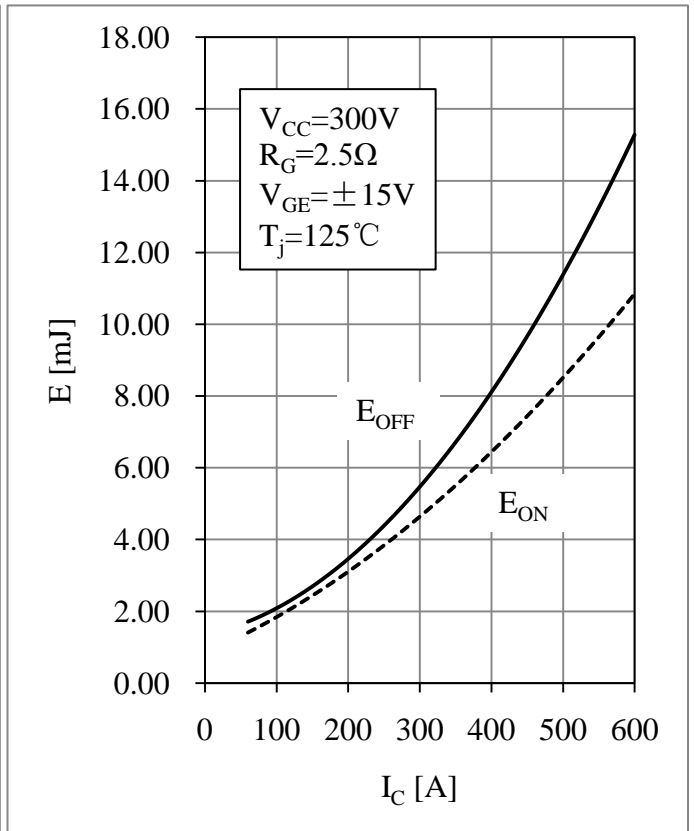


Fig 12. IGBT Switching Loss vs. I_C (T3,T4)

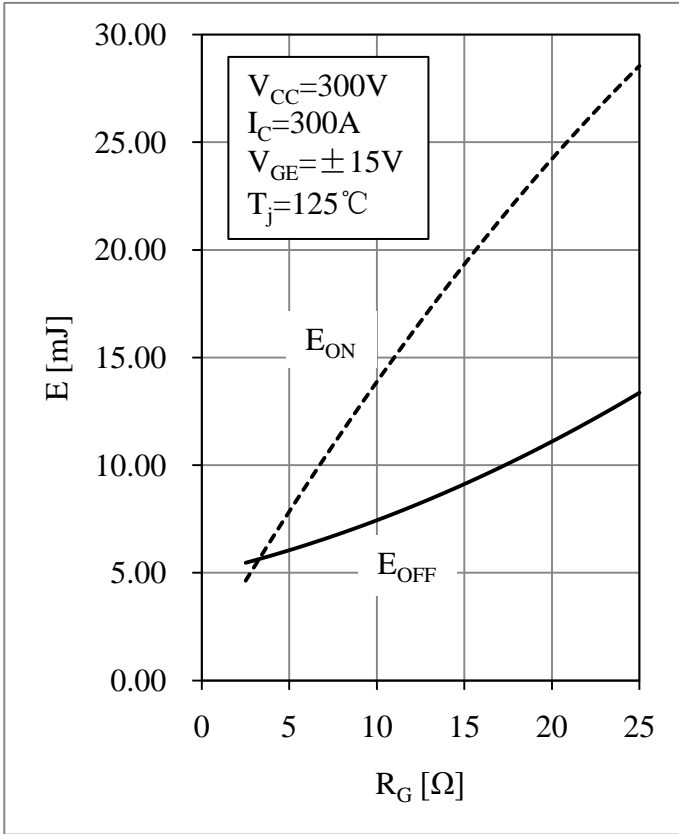


Fig 13. IGBT Switching Loss vs. R_G (T3,T4)

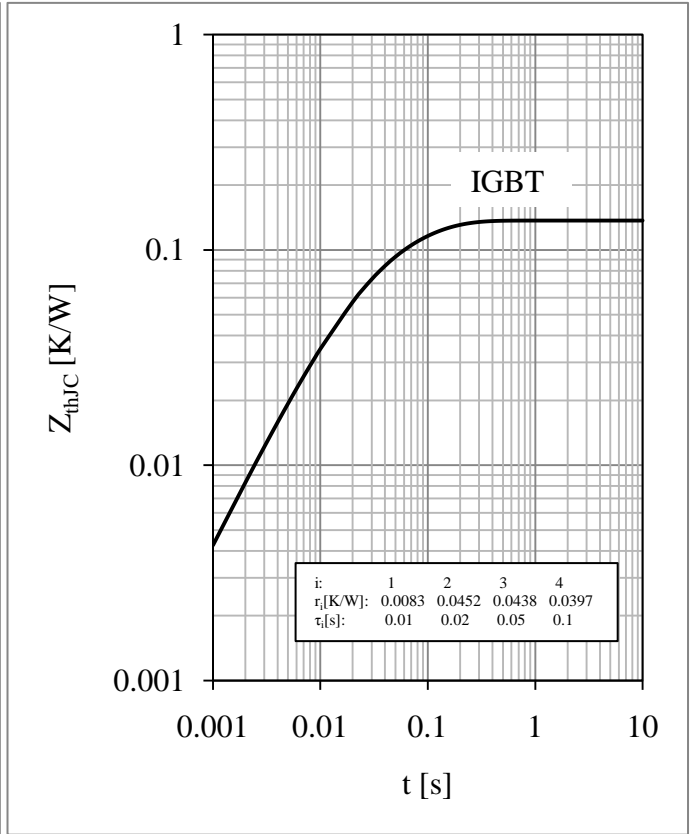


Fig 14. IGBT Transient Thermal Impedance (T3,T4)

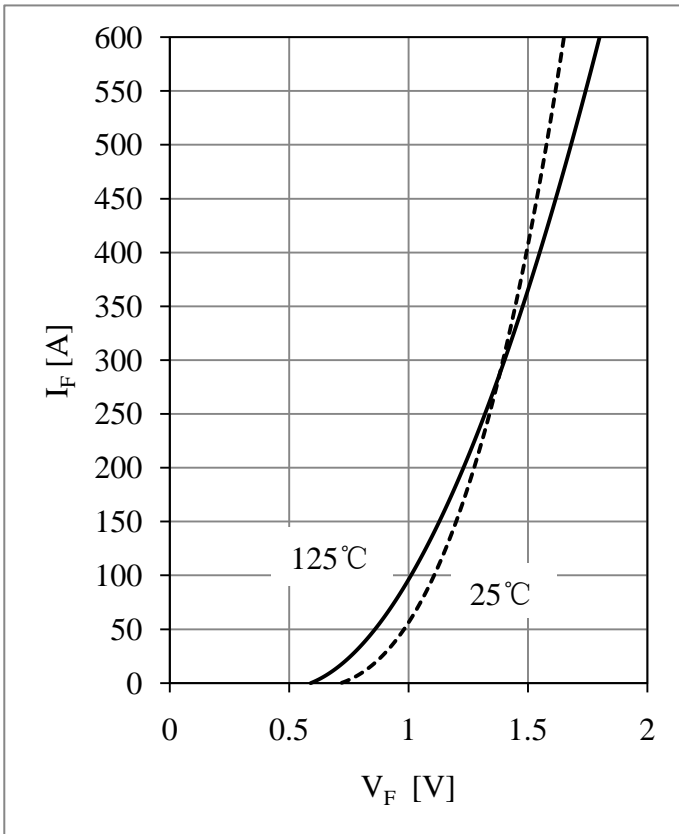


Fig 15. Diode Forward Characteristics (T3,T4)

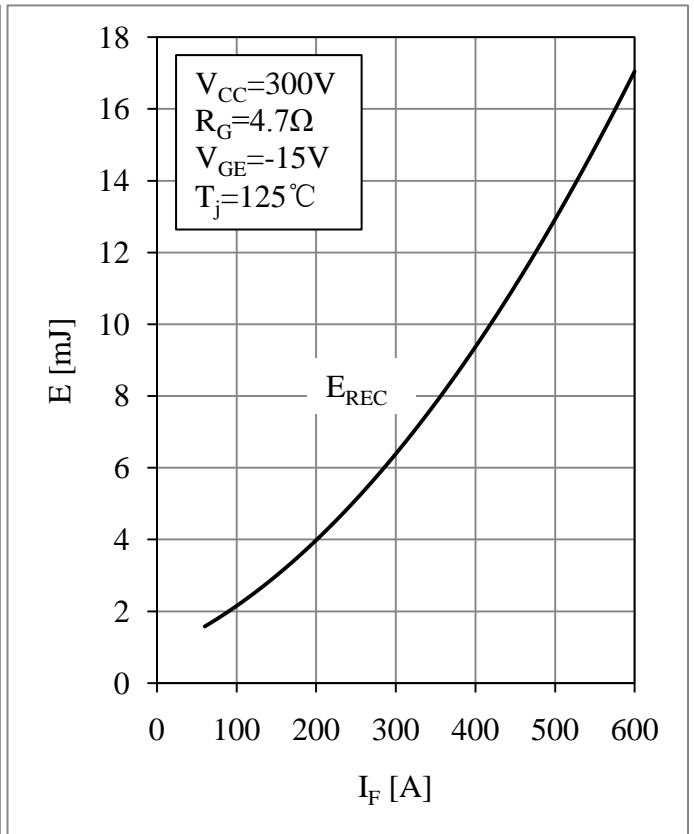


Fig 16. Diode Switching Loss vs. I_F (T3,T4)

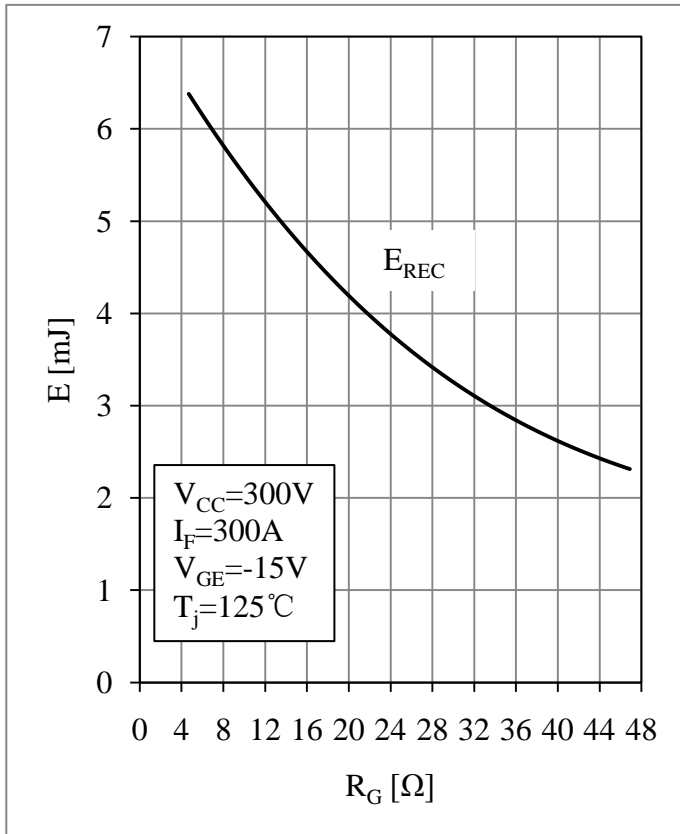


Fig 17. Diode Switching Loss vs. R_G (T3,T4)

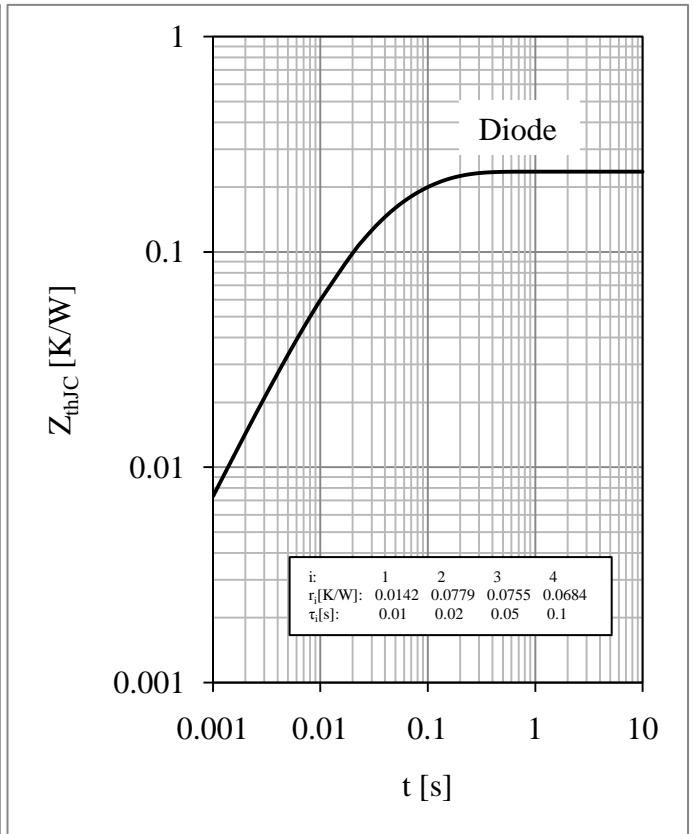
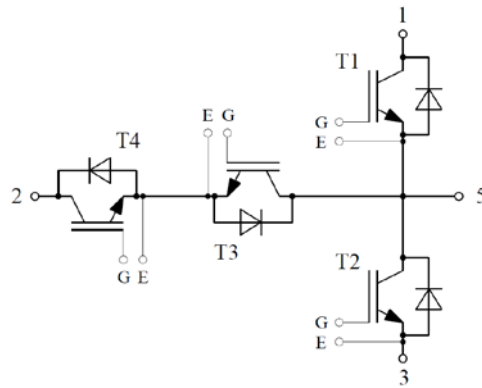


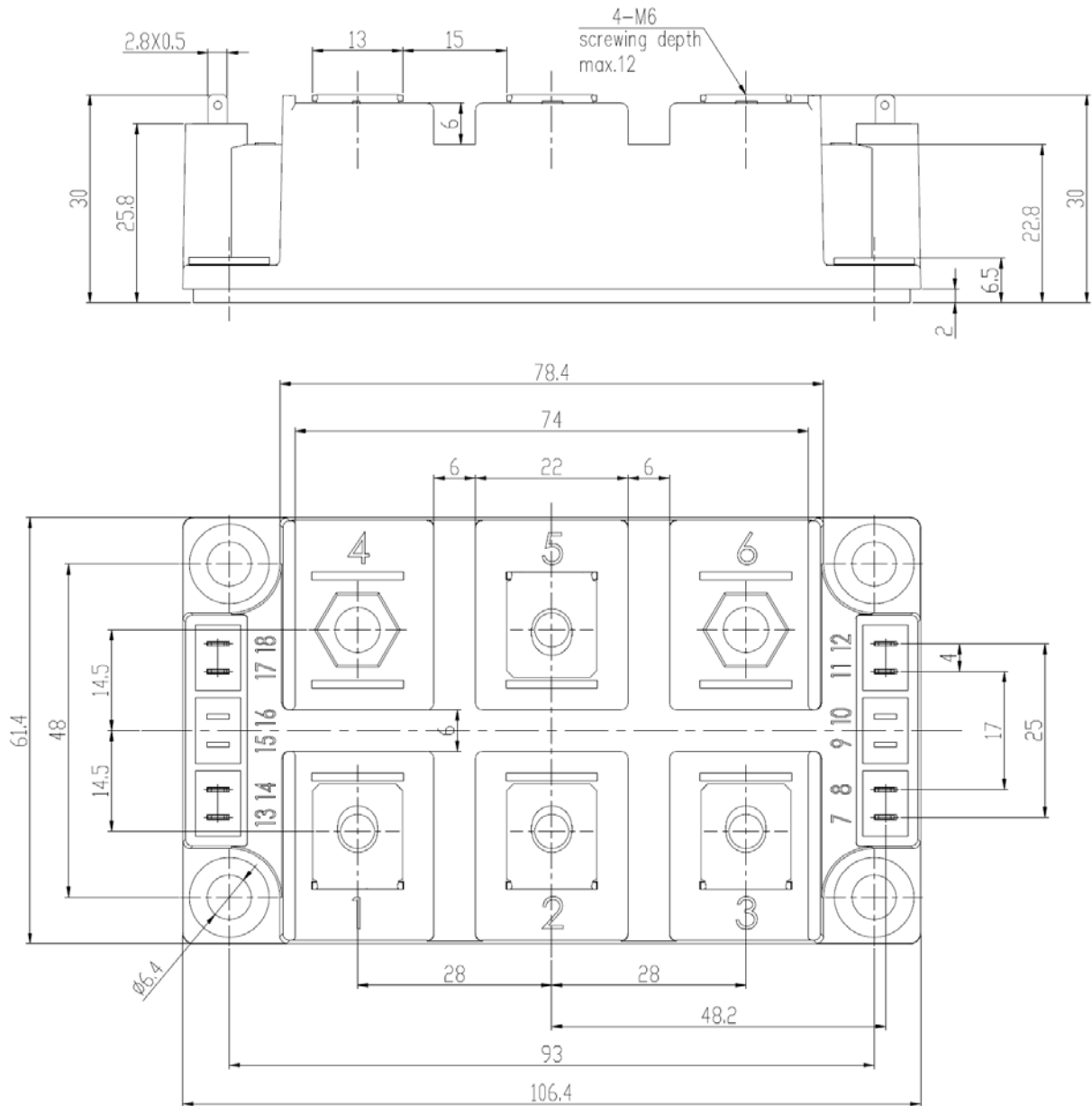
Fig 18. Diode Transient Thermal Impedance (T3,T4)

Equivalent Circuit Schematic



Package Dimension

Dimensions in Millimeters



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